



FEATURES

- DM03/04 SERIES conforms to JEDEC standards
- Memory Module Board is retained in the socket by metal latches.
- Easy insertion and withdrawal of Memory Module Board
- Metal latches are highly reliable.
- TSOP DRAM or other components can be mounted beneath DM03/04 socket
- RoHS compliance

SPECIFICATIONS

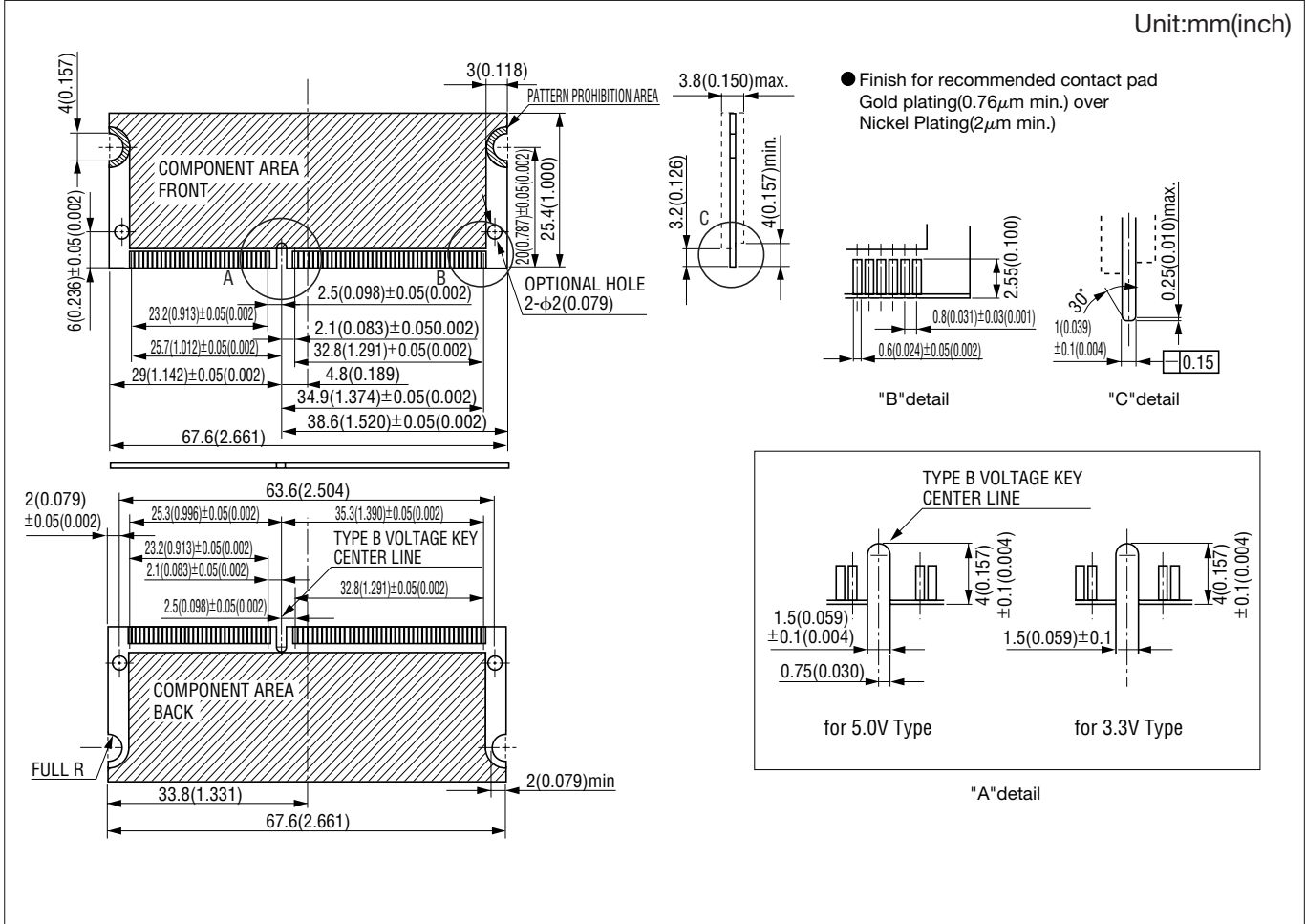
- Insulator : LCP UL94V-0
- Contact : Phosphor Bronze
- Plating : Contact area ; Gold over Nickel
Terminal area ; Gold over Nickel
- Latch material : Copper alloy
- Latch plating : Tin copper over Nickel
- Current rating : 0.5A per contact
- Contact resistance : 50mΩmax
- Withstanding voltage : 250V AC for 1 minute
- Insulation resistance : 500MΩmin. at 250V DC
- Temperature : -55°C to +85°C

● ORDER CODE

DM [] -144 [] -F

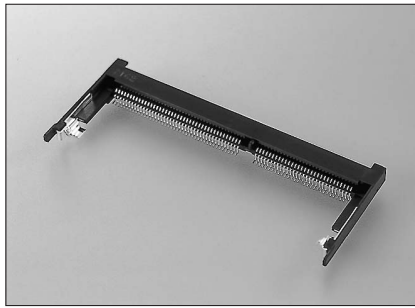
- **F** : RoHS Compliance
- Type
 - 1 : For 5.0 Volt
 - 2 : For 3.3 Volt
- Contact plating
 - B : Gold plating 0.1μm min
- Number of contact
 - 144 : 144pin
- Series name
 - DM03 : 4.0mm(0.1572") for mounted height
 - DM04 : 5.2mm(0.205") for mounted height

Recommended Memory Module Board Layout

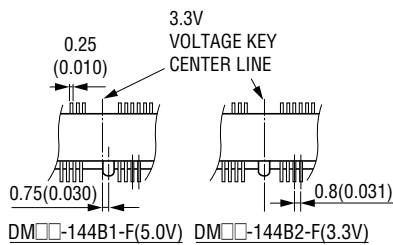
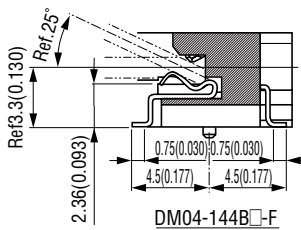
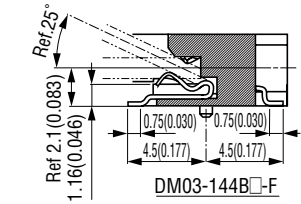


DM□□-144□□-F

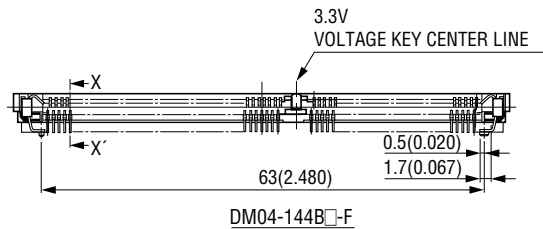
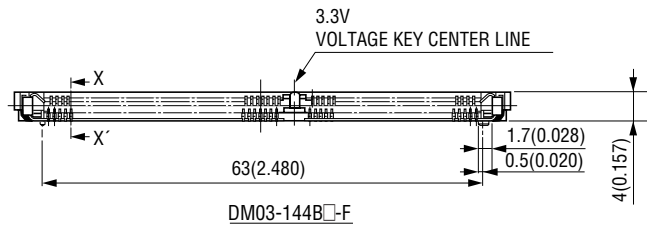
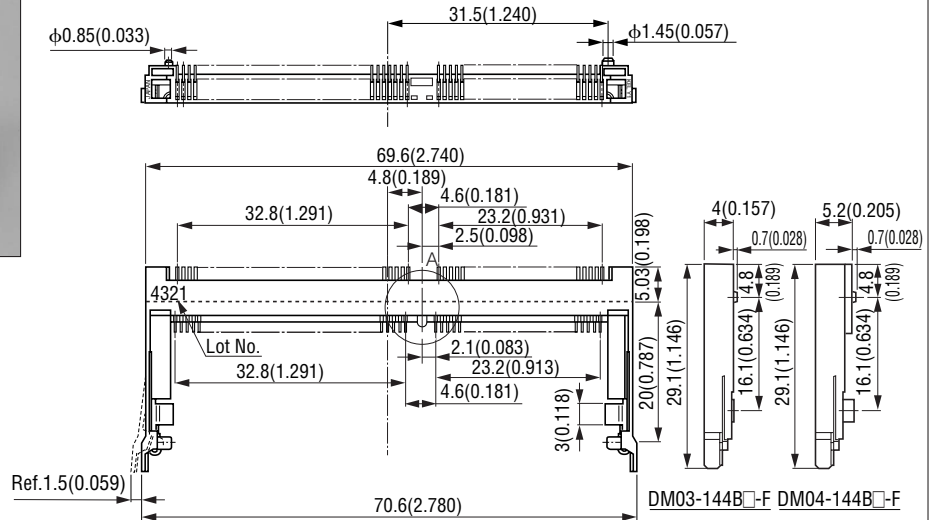
Unit:mm(inch)



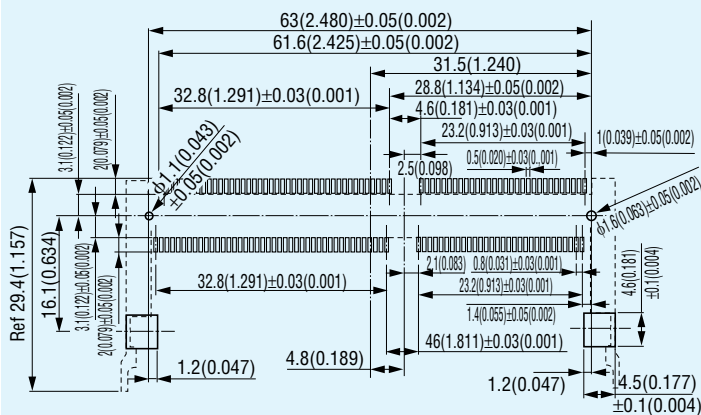
X-X' Cross Section



"A" detail



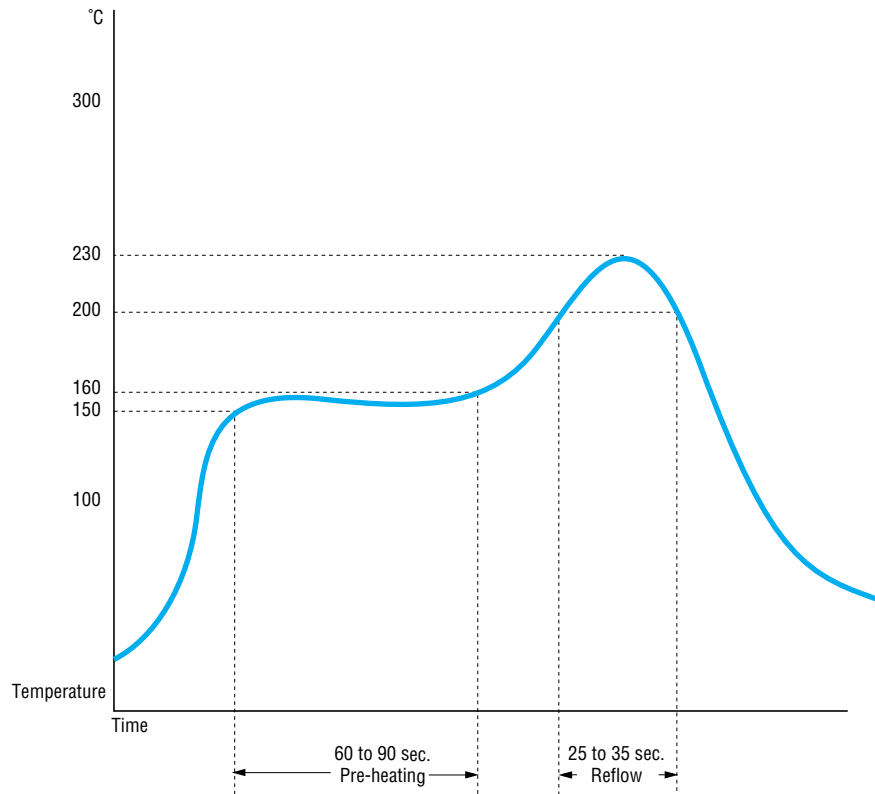
Recommended PCB Layout
(Component Side View)



Recommended Temperature Profile for IR reflow

- Temperature : 300 or lower three seconds(Max.)

Unit:mm(inch)



Notes:

- 1 . Solder flux should be applied to PCB and not to contact tails
- 2 . Recommended stencil thickness for cream solder is 0.15mm(0.006")

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Specifications and dimensions are subject to change without notice